

QF2036L

No Clean Liquid Flux



Product Description

QF2036L is a low solid content flux, chemically and electrically stable under various operating environments. QF2036L is specially designed to deliver the best of solderability and minimize micro-solderballs for conventional and circuit board assemblies. This no-clean and clear residue flux shows superior wetting on difficult-to-solder substrates. It is compatible with lead free applications.

Application

QF2036L is specially formulated for spraying, foaming as well as dipping (Cu substrate) processes. Recommended onboard preheat temperature is 80 – 100 °C.

Residue Removal

Since the residues are minimal and non-corrosive, removal is usually not required. If cleaning is required, the flux residue could be removed by any solvent or aqueous flux cleaner available in the market.

Recommended Solvent

Asahi's complementary Solvent #2000. Solvent can be stored for about 2 years under normal storage conditions of 25°C.

Health and Safety

Observe standard precautions for handling and use, such as well-ventilated areas and avoidance of prolonged or repeated contact with the skin. For more information, please refer to the Material Safety Data Sheet.

Storage

Under proper storage condition, QF2036L can be stored for up to 6 months. QF2036L is flammable. Keep away from all sources of heat, sparks, flame and sunlight.

Packaging

Available in 18kg/carboy.

Specification

Item	Result
State	Liquid
Colour	Very pale yellow
Specific Gravity @ 25°C	0.795 +/- 0.005
JIS Z 3197 8.2.2	
Non-volatile Solid Content	
JIS Z 3197 8.1.3	3.6 +/- 0.2 wt%
Halide Content	Not Detected
JIS Z 3197 8.1.4.2.1	
Acid Value Test	19.5 +/- 2 mg KOH/g flux
IPC-TM-650 2.3.13	
JIS Z 3197 8.1.4.1	
Water Extract Resistivity	> 5 x 10 ⁴ Ω-cm
JIS Z 3197 8.1.1	
Surface Insulation Resistance (85°C, 85%RH, 168hrs)	
IPC-TM-650 2.6.3.3	> 1 x 10 ⁸ Ω, Pass
JIS Z 3197 8.5.3	> 1 x 10 ¹¹ Ω, Pass
Electromigration (85°C, 88.5%RH, 596hrs)	Pass
IPC-TM-650 2.6.14.1	
Copper Corrosion Test	Pass
IPC-TM-650 2.6.15	
JIS Z 3197 8.4.1	
Copper Mirror Test	Classified as "L", Pass
IPC-TM-650 2.3.32	
JIS Z 3197 8.4.2	
Flux Activity Classification	ROLO
IPC J-STD-004	
Spread Factor	> 75% (SCS7)
JIS Z 3197 8.3.1.1	
Residue Dryness Test	Dry
IPC-TM-650 2.4.47	
JIS Z 3197 8.5.1	
Surface Finish	Shiny

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